

Product Overview

NSD11416-Q1 is a 160mΩ low-side switch with 48V clamp voltage for automotive applications. It's designed for driving resistive or inductive loads with one side connected to the battery. Internal 48V clamp circuit protects device from surge energy when fast demagnetization at turn-off.

With internal output current limitation, the device is protected in overload condition. Built-in thermal shutdown protects the chip from over-temperature and short-circuit. A thermal swing mechanism is built to limit dissipated power to decelerate power accumulation. Thermal shutdown, with automatic restart, allows the devices to recover normal operation as soon as a fault condition disappears.

An internal diagnose function is built to indicate any faults when thermal shutdown and short circuit to ground conditions through an open-drain status output pin. This device operates in ambient temperatures from -40°C to 125°C.

Applications

- Automotive Relays
- Valves
- Solenoid drivers
- Lighting

Device Information

Part Number	Package	Body Size
NSD11416-Q1SPR	SO-8	4.9 mm x 3.9 mm
NSD11416-Q1STBR	SOT223	6.48mm x 3.38mm

Key Features

- AEC-Q100 (Grade 1) qualified for automotive application
- Drain current limitation: 2.5A
- 48V overvoltage clamp
- Thermal shutdown protection
- Thermal swing protection
- Fault diagnostic block
 - Thermal shutdown diagnosis
 - Short circuit to ground diagnosis
- Very low standby current
- Very low electromagnetic susceptibility
- ESD protection
- RoHS & REACH Compliance

Typical Application

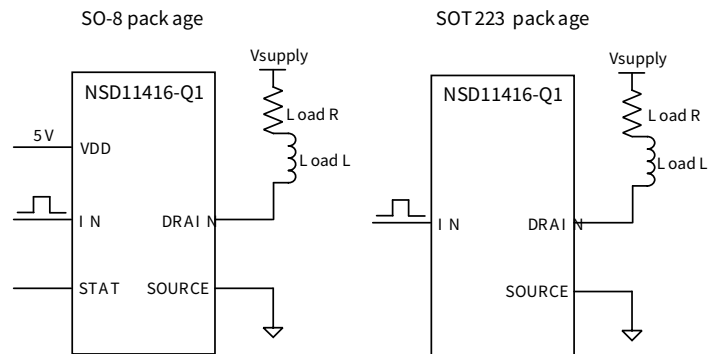


Figure 0.1 NSD11416-Q1 Typical Application

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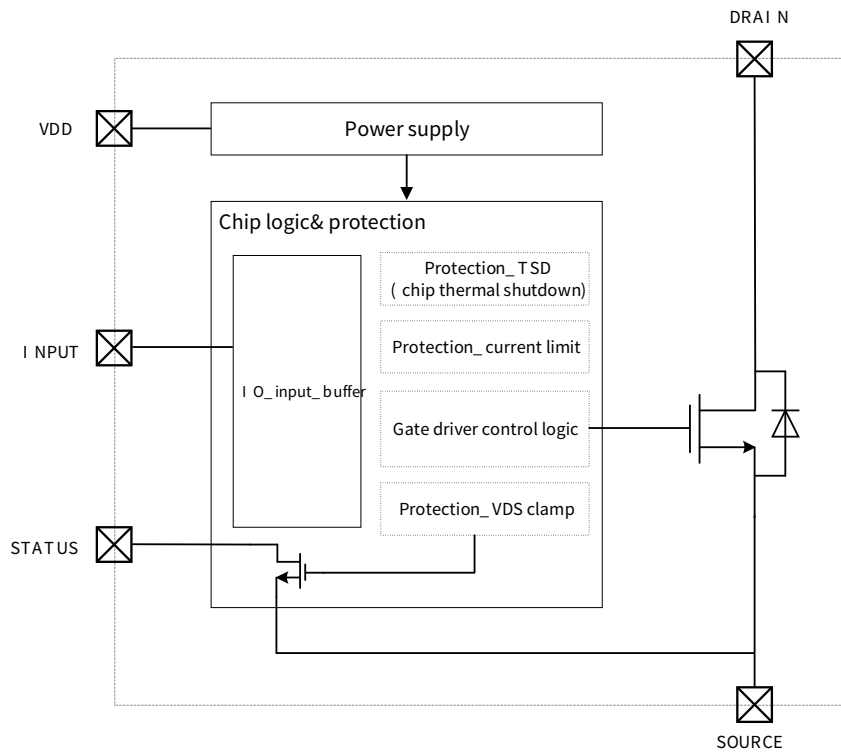


Figure 2.1 NSD11416-Q1SPR (SO-8) Block diagram

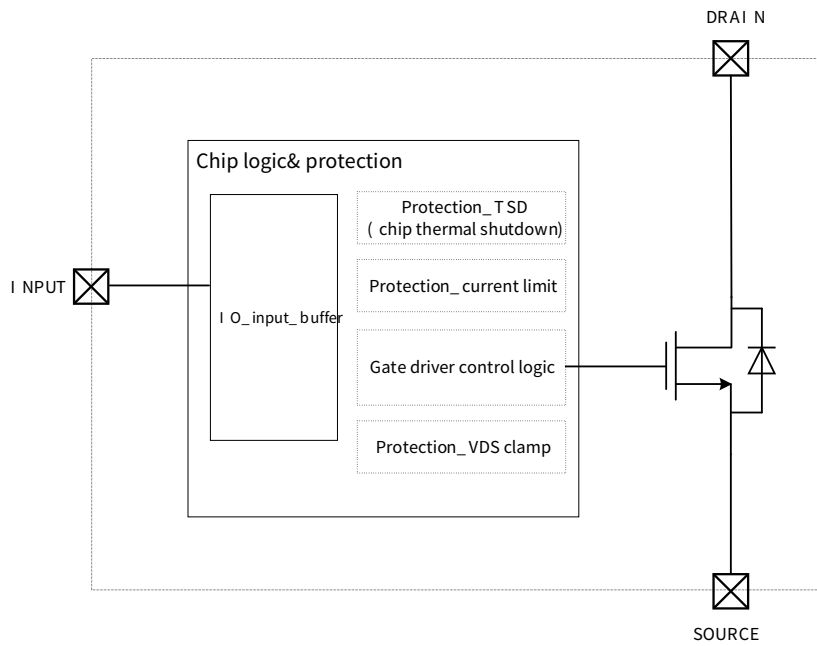


Figure 2.2 NSD11416- Q1STBR (SOT223) Block diagram

Absolute Maximum Ratings

Parameters	Symbol	Min	Typ	Max	Unit
Drain-to-Source Voltage	V_{DS}			Internally clamped	V
DC Drain Current	I_D			Thermal limited	A
VDD Pin Current	I_{VDD}	-1		10	mA
INPUT Pin Current	I_{IN}	-1		10	mA
STATUS Pin Current	I_{TAT}	-1		10	mA
Junction Temperature	T_J	-40		150	°C
Storage Temperature	T_{stg}	-55		150	°C
Single pulse avalanche energy ($L = 30\text{mH}$; $T = 150\text{ }^\circ\text{C}$; $I_{L} = 0$; $d_{JT} = 2.2\text{A}$)	E_{AS}			37	mJ

Electrostatic Discharge

Parameters	Symbol	Value	Unit
V(ESD) Electrostatic discharge	Human-body model, per AEC-Q100-002-RevD, $V_{ESD-HBM}$	± 4000	V
	Charged-device model, per AEC-Q100-011-RevB, $V_{ESD-CDM}$	± 750	V

Thermal Information

Parameters	Symbol	Min	Max	Unit
Junction-to-ambient Thermal Resistance	θ_A	96.3	76.3	°C/W
Junction-to-top characterization parameter	ψ_T	8.75	7.5	°C/W
Junction-to-case (top) thermal resistance	$\theta_{JC(top)}$	49.3	46.9	°C/W

The thermal data is based on the JEDEC standard high-K profile, JEDEC 51-7, four layers board.

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($V_{DD} = V_{IN} = 4.5\text{ V to }5.5\text{ V}$, $T = -40^\circ\text{ C to }150^\circ\text{ C}$. Unless otherwise noted.)

Para eters	y bol	M n	yp	Max	unt	Co ents
Power MO FE						
Operating supply voltage	V_S	3.5	5	5.5	V	
ON-state resistance	R_{ON}		160		m Ω	$I_D = 1\text{ A}$; $T = 25^\circ\text{ C}$; $V_{DS} = V_{IN} = 5\text{ V}$
				320	m Ω	$I_D = 1\text{ A}$; $T = 150^\circ\text{ C}$; $V_{DS} = V_{IN} = 5\text{ V}$
Drain-source clamp voltage	V_{CLAMP}	46	48	56	V	$V_{IN} = 0\text{ V}$, $I_b = 1\text{ A}$
Drain-source clamp threshold voltage	V_{CLTH}	40			V	$V_{IN} = 0\text{ V}$, $I_b = 2\text{ mA}$
OFF -state output current	I_{DSS}	0		3	μA	$V_{IN} = 0\text{ V}$; $V_S = 13\text{ V}$; $T = 25^\circ\text{ C}$
		0		5	μA	$V_{IN} = 0\text{ V}$; $V_S = 13\text{ V}$; $T = 125^\circ\text{ C}$
Body diode forward voltage	V_{BD}		0.8		V	$I_D = 1\text{ A}$; $V_{DS} = 0\text{ V}$
Input sect on O pac age on ly						
Supply current from input pin	I_{ISS}		30	65	μA	ON-state: $V_{DS} = V_{IN} = 5\text{ V}$; $V_S = 0\text{ V}$
Input clamp voltage	V_{CL}	5.5		8	V	$I_S = 1\text{ mA}$
			-0.7			$I_S = -1\text{ mA}$
Input threshold voltage	V_{NTH}	1		3.5	V	$V_{DS} = V_{IN}$, $I_D = 1\text{ mA}$
DD O pac age on ly						
Operating supply current	I_S		10	25	μA	OFF -state; $T = 25^\circ\text{ C}$; $V_{IN} = V_{DS} = 0\text{ V}$;
			25	65	μA	ON-state; $V_{IN} = 5\text{ V}$; $V_{DS} = 0\text{ V}$
Supply clamp voltage	V_{SCL}	5.5		8	V	$I_{SCL} = 1\text{ mA}$
			-0.7			$I_{SCL} = -1\text{ mA}$
Log c Input O pac age on ly						

Parameters	Symbol	Min	Typ	Max	Unit	Conditions
High-level input current	I_{IH}			10	μA	$V_{IN} = 2.2\text{V}$
Input hysteresis voltage	$V_{(hyst)}$	0.13			V	
Input clamp voltage	V_{CL}	5.5		8	V	$I_{IN} = 1\text{mA}$
			-0.7			$I_{IN} = -1\text{mA}$
Status indicator - Q package only						
Status low output voltage	V_{STAT}			0.5	V	$I_{STAT} = 1\text{mA}$
Status leakage current	I_{STAT}			10	μA	$V_{STAT} = 5\text{V}$
Status pin input capacitance	C_{STAT}			100	pF	$V_{STAT} = 5\text{V}$
Status clamp voltage	V_{STCL}	5.5		8	V	$I_{STAT} = 1\text{mA}$
			-0.7			$I_{STAT} = -1\text{mA}$
Short circuit to ground detection - Q package only						
Short circuit to ground OFF-state voltage detection threshold	V_{SCGTH}	1.1	1.2	1.4	V	$V_{IN} = 0\text{V}$
Delay between I NPUT falling edge and STATUS falling edge in short circuit to ground condition	$t_{d(STAT)}$		225		μs	$I_{OUT} = 0\text{A}$
Switching characteristics						
Turn-on delay time	$t_{d(ON)}$		9		μs	$R_L = 13\ \Omega, V_C = 13\text{V}$
Turn-off delay time	$t_{d(OFF)}$		9		μs	$R_L = 13\ \Omega, V_C = 13\text{V}$
Rise time	t_r		9		μs	$R_L = 13\ \Omega, V_C = 13\text{V}$
Fall time	t_f		5		μs	$R_L = 13\ \Omega, V_C = 13\text{V}$
Switching energy losses at turn-on	W_{ON}		26		μJ	$R_L = 13\ \Omega, V_C = 13\text{V}$
Switching energy losses at turn-off	W_{OFF}		23		μJ	$R_L = 13\ \Omega, V_C = 13\text{V}$
Protection and diagnostics						
DC short-circuit current	I_{lim}	1.6	2.5	3	A	$V_S = 13\text{V}, V_D = V_{IN} = 5\text{V}$
Shutdown temperature	T_{TSD}	150	175	200	$^{\circ}\text{C}$	
Reset temperature	T_R	$T_{RS} + 1$	$T_{RS} + 5$		$^{\circ}\text{C}$	
Thermal reset of STATUS	T_{RS}	135			$^{\circ}\text{C}$	
Thermal hysteresis ($T_{SD} - T_R$)	T_{HYS}		7		$^{\circ}\text{C}$	
Dynamic temperature	ΔT_J		40		$^{\circ}\text{C}$	$T_J = -40^{\circ}\text{C}, V_C = 13\text{V}$
Dynamic temperature hysteresis	$\Delta T_{J(HYS)}$		15		$^{\circ}\text{C}$	

6.2. Typical Performance Characteristics

Table

Conditions	Input	Drain	Status
Normal operation	L	H	H
	H	L	H
Current limitation	L	H	H
	H	X	H
Over-temperature limitation	L	H	H
	H	H	L
VDD under-voltage	L	H	X
	H	H	X
Short circuit to ground	L	L	L
	H	L	H

Switching characteristics

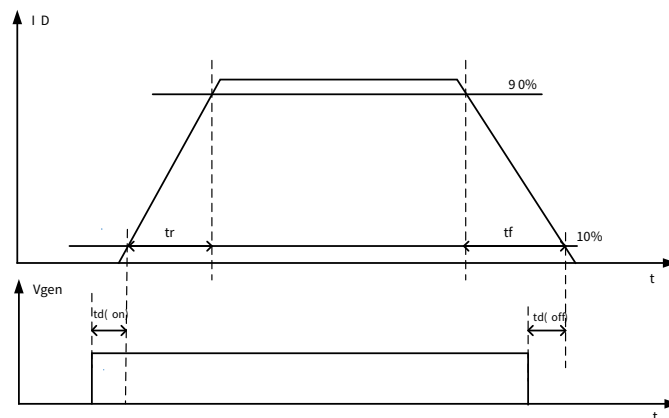


Figure 6.2.2 NSD11416-Q1 Switching Characteristics

Protections

Current Limitation

NSD11416-Q1 has current limitation to protect the silicon and bonding wire in case of overload or short circuit to battery.

Thermal Shutdown and Thermal Warning

This device has both absolute and dynamic temperature protection. There are two thermal sensors on the controller and the MOSFET, the one on the MOSFET is the hottest and the one on the controller is the coldest. The absolute temperature protection is to shut down the MOSFET when the hottest junction temperature exceeds the T_{SD} , and the dynamic temperature protection is also to shut down the MOSFET when the temperature difference between the hottest and the coldest exceeds ΔT_J .

Application for motor

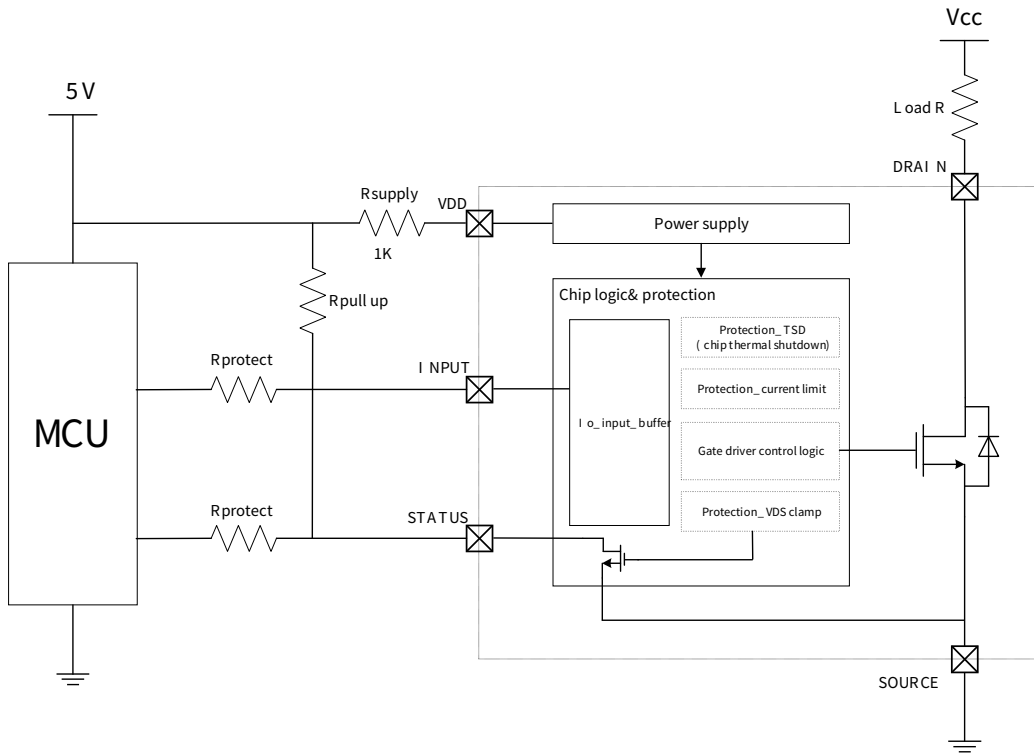


Figure 8.1 NSD11416-Q1SPR application schematic

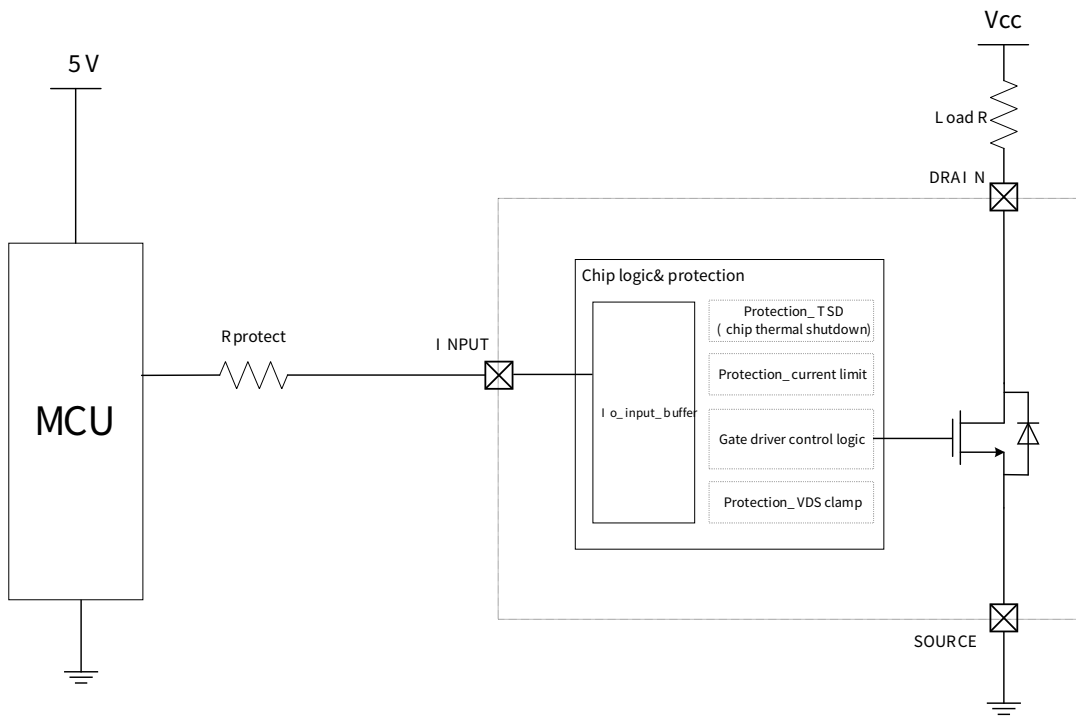


Figure 8.2 NSD11416-Q1STBR application schematic

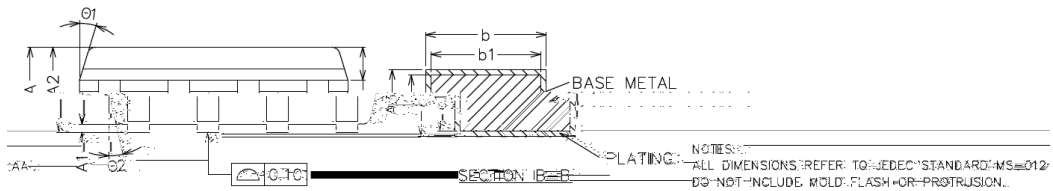
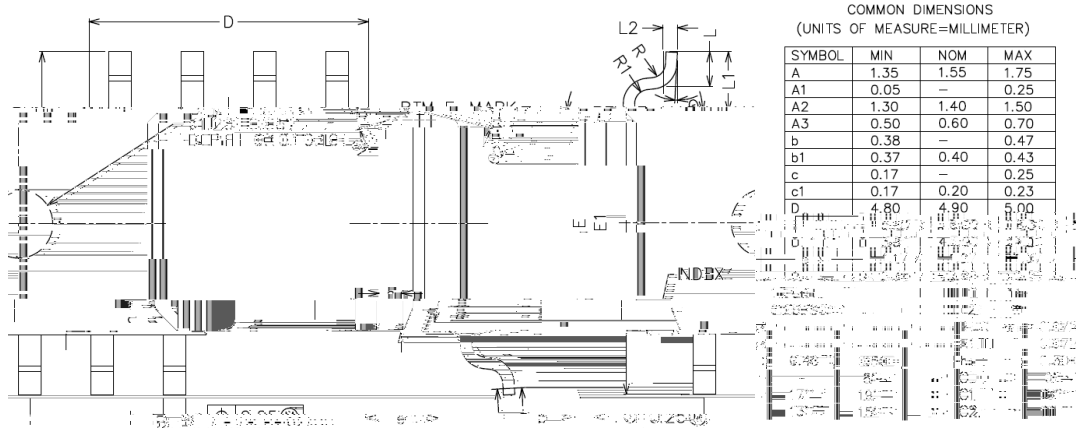
MCU I/O protection

NSD11416 has Zener diodes inside for ESD protection and the intrinsic NPN parasitic bipolar, so that resistors for protection are necessary in series with the digital inputs to limit the current to protect MCU I / Os during transient and reverse battery conditions.

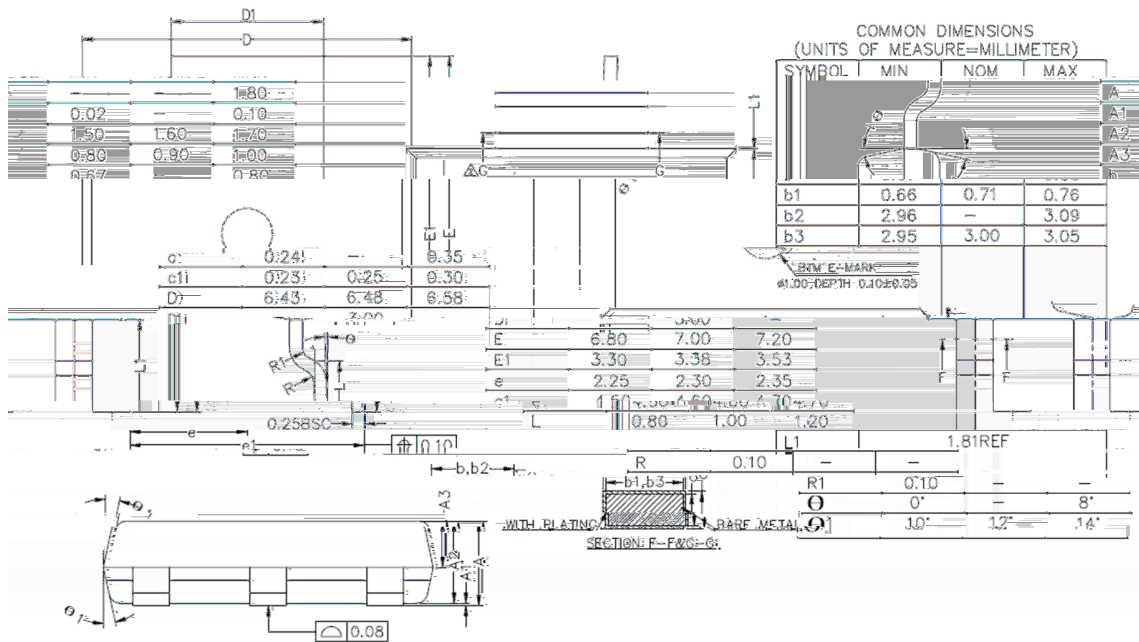
The value of resistors for protection can be calculated by the formula as shown below:

Package Information

0 Package Information

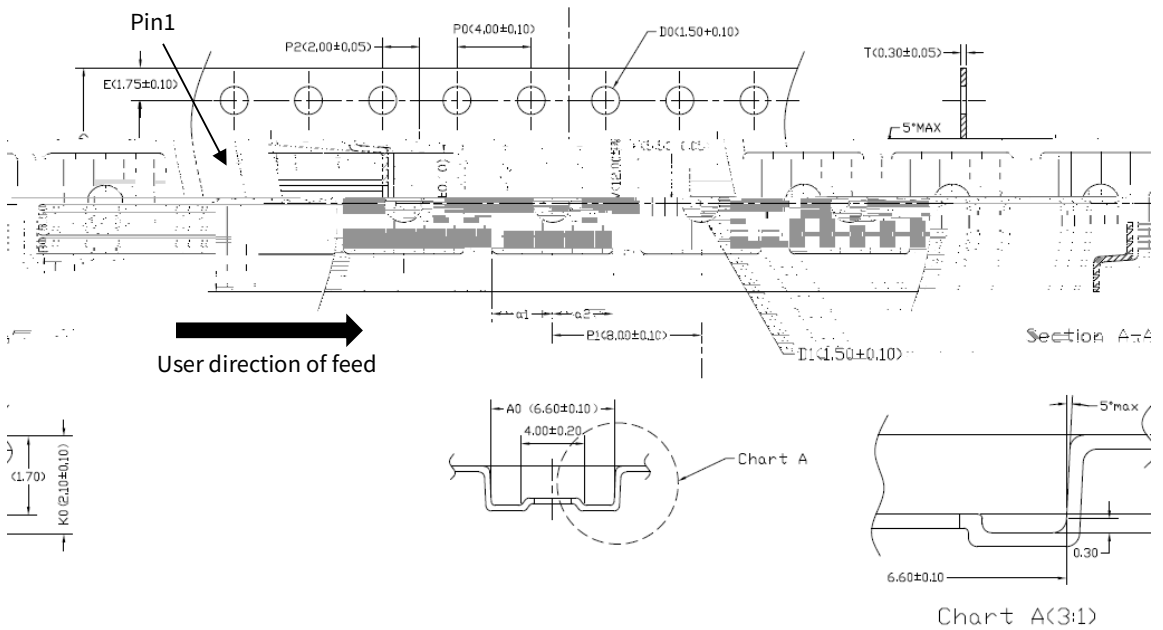
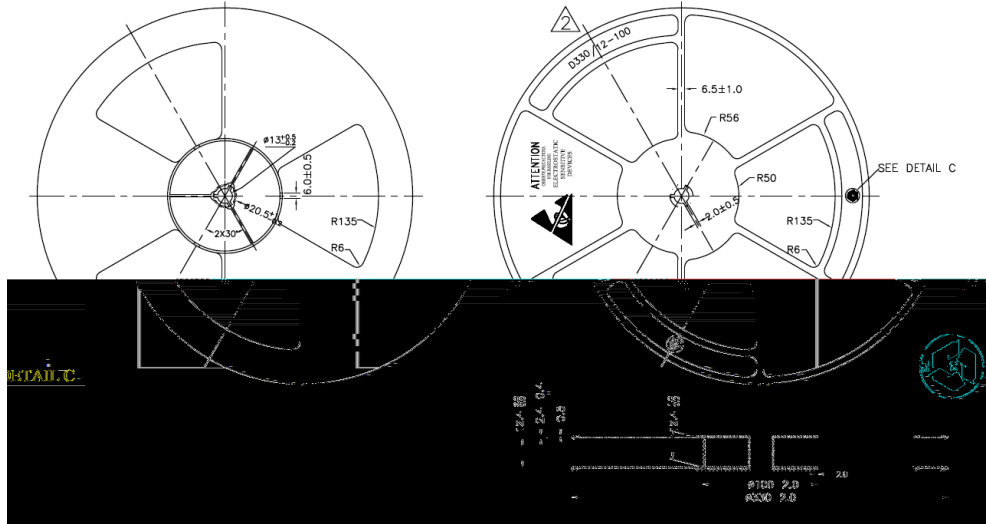


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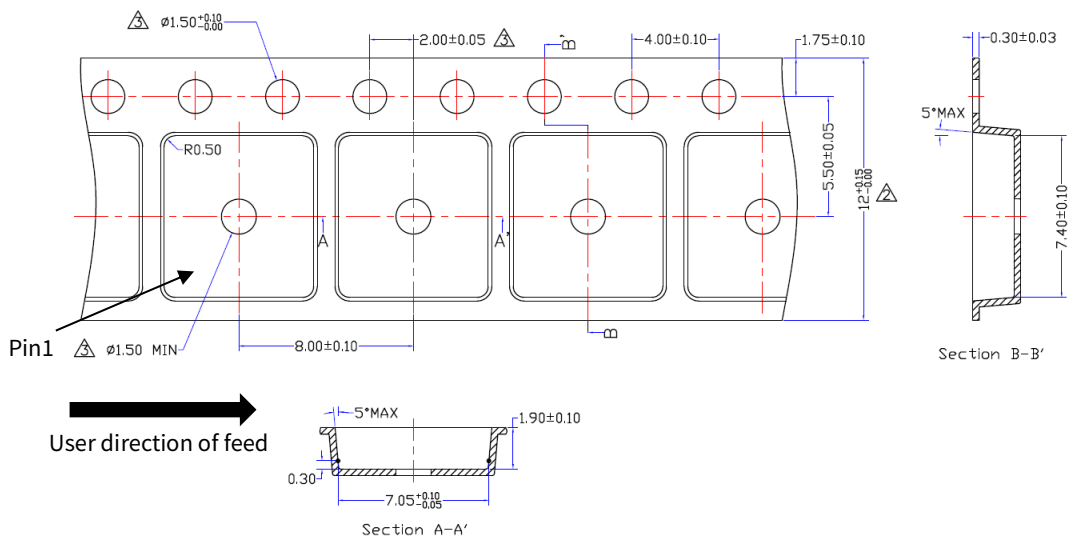
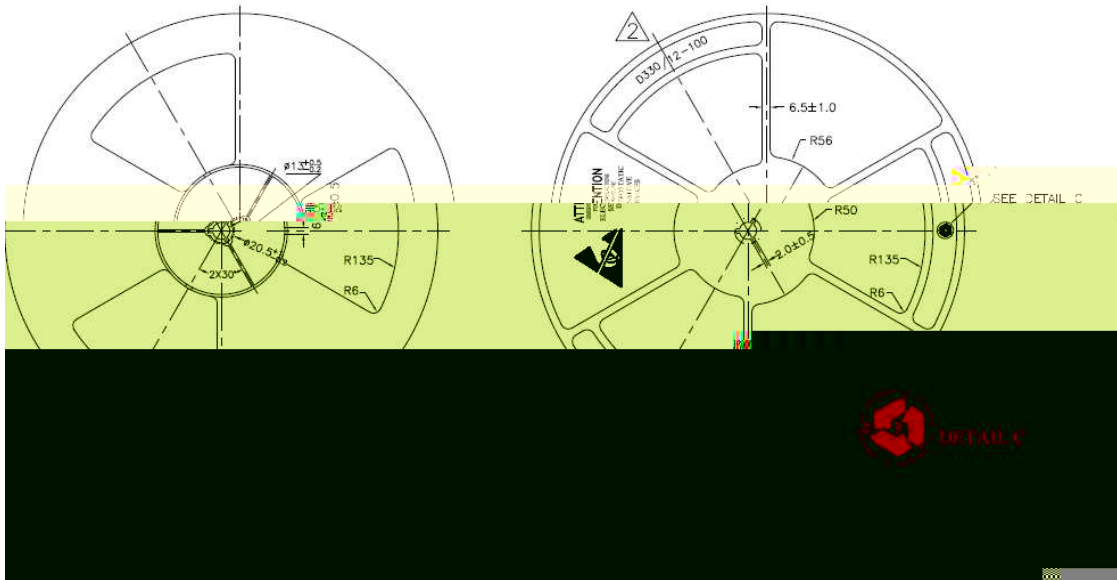


Packaging Information

0 Packaging Information



10.2.SOT223 pac a!in! information



Order ng Infor at on

Part Nu ber	Pac age	M L	PQ
NSD11416-Q1SPR	SO-8	3	25 00
NSD11416-Q1STBR	SOT223	3	25 00
Note: All pack ages are ROHS compliant with peak reflow temperature of 260° C according to the J EDEC industry standard classifications and peak solder temperature.			

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ev s on	Descr pt on	Date
1.0	I nitial version	2024/ 1/ 31
1.1	Update description	2024/ 3/ 15
1.2	Update “ short circuit to ground OF F-state voltge detection threshold” max value	2024/ 4/ 7

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